

FIG. 3A

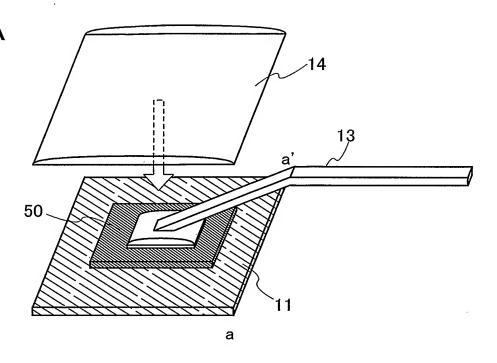
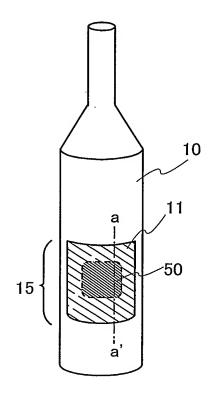
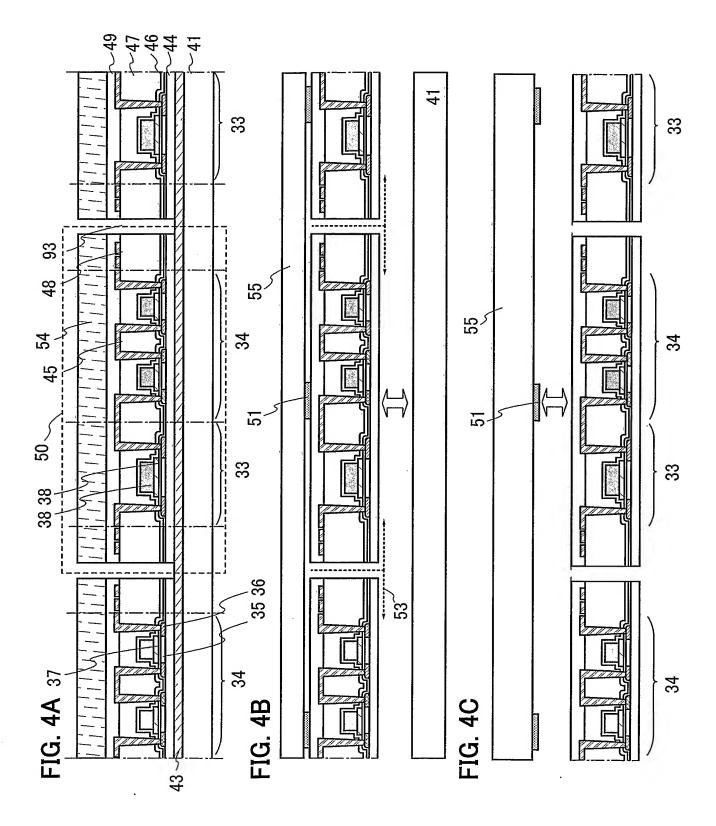


FIG. 3B





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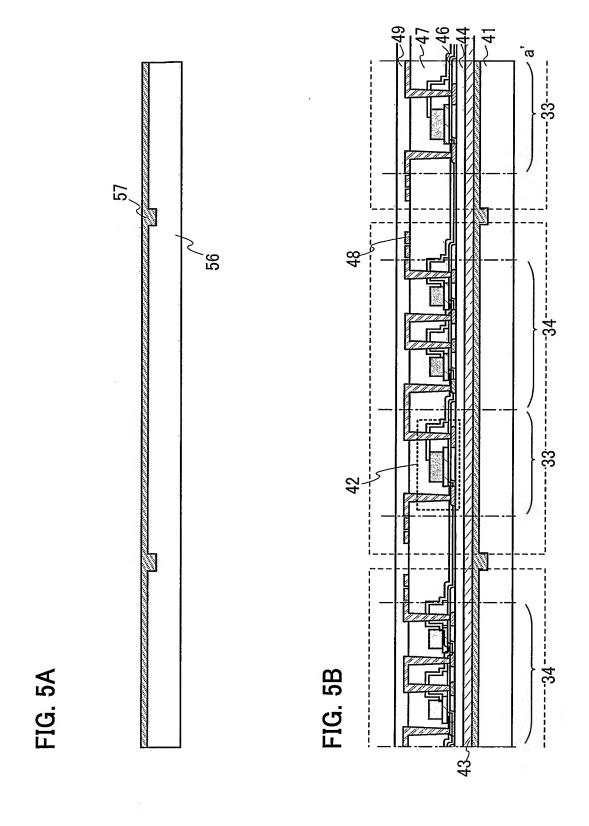


FIG. 6A

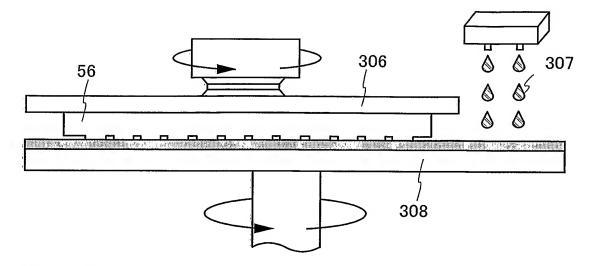
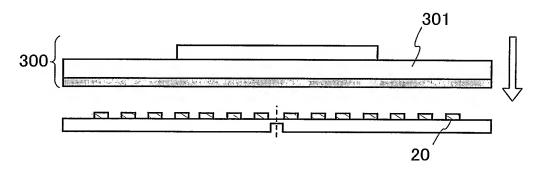
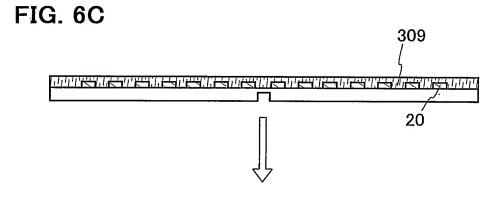
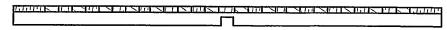


FIG. 6B







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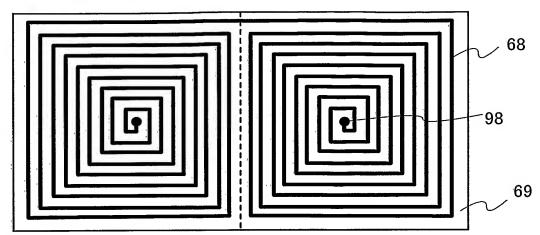
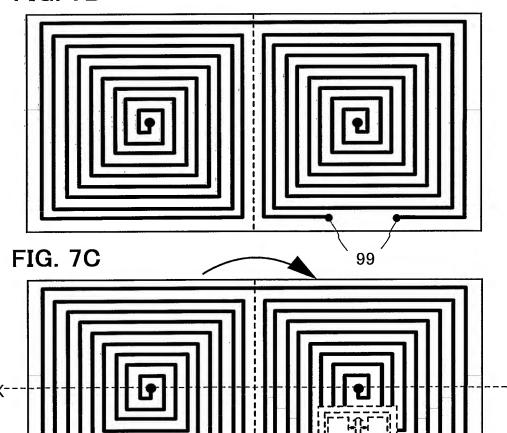
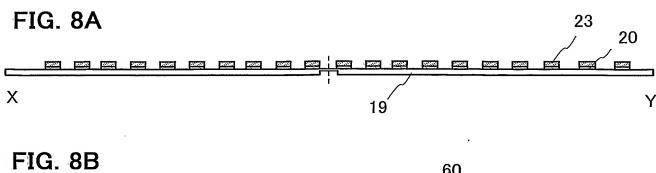


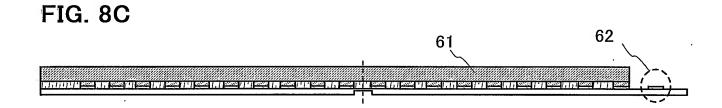
FIG. 7B



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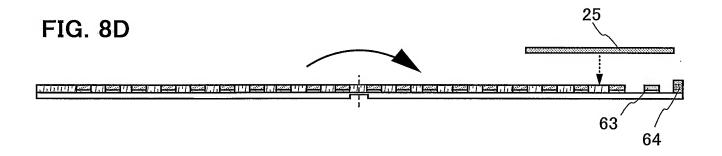


FIG. 8E

भू काल मार्च अरूप मार्च अरूप मार्च करन मार्च अरूप मार्च करने मार्च अरूप मार्च अरूप मार्च अरूप मार्च अरूप मार्च	बद्धाता र
was the way	7 Ⅲ ≻66
	

FIG. 9A

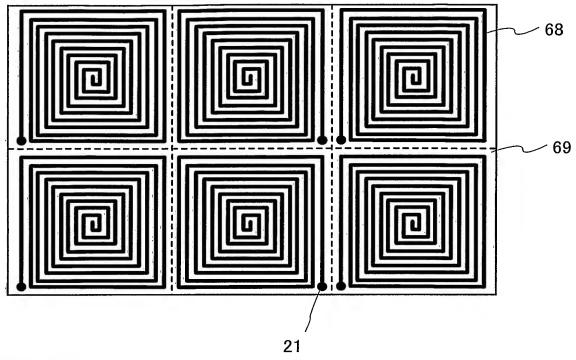
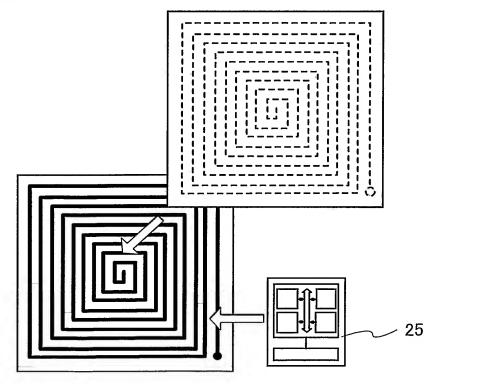


FIG. 9B



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FIG. 10A

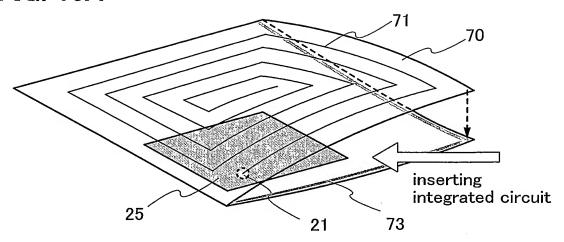
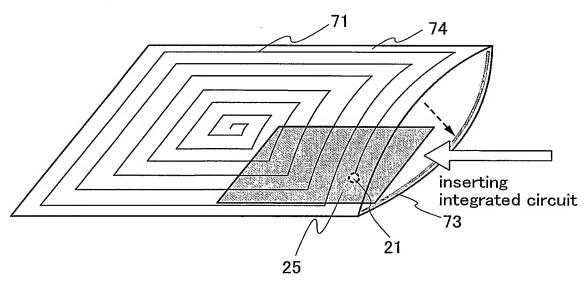


FIG. 10B



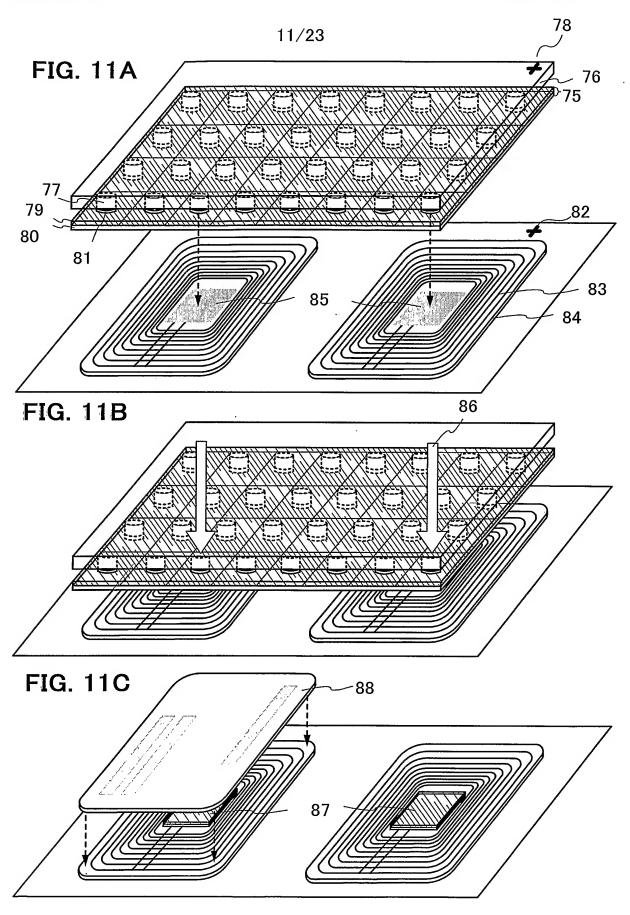
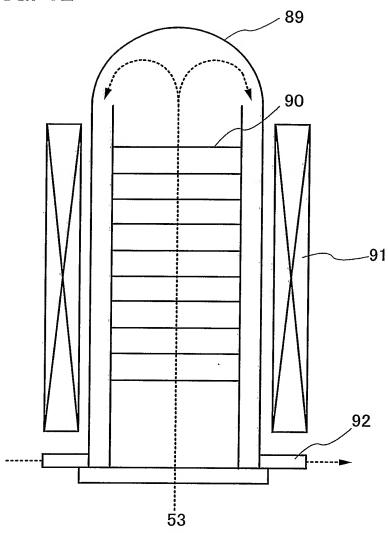


FIG. 12



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FIG. 13A

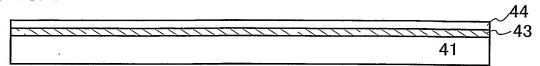


FIG. 13B

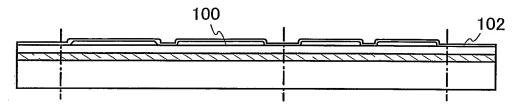


FIG. 13C

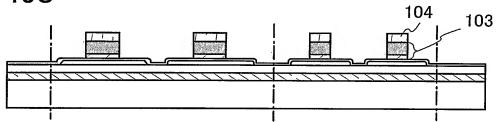


FIG. 13D

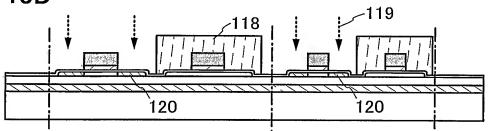
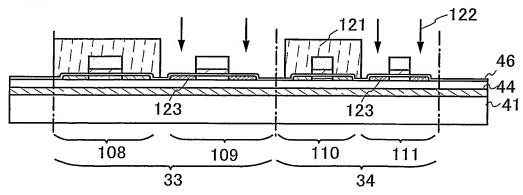


FIG. 13E



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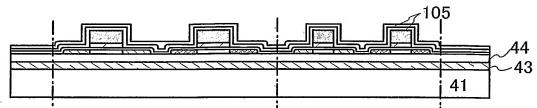


FIG. 14B

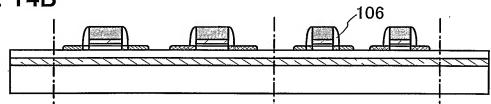


FIG. 14C

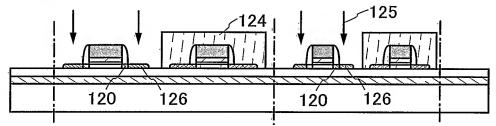


FIG. 14D

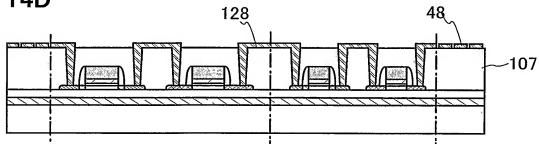
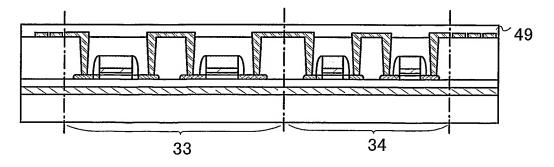


FIG. 14E



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FIG. 15A

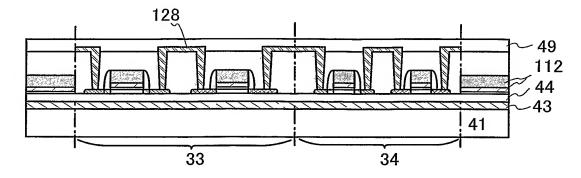


FIG. 15B

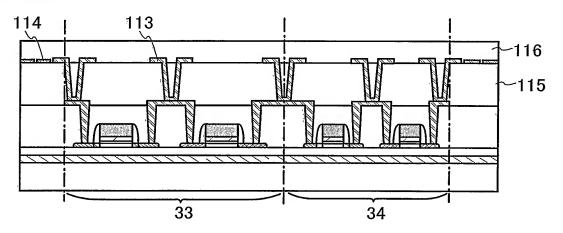


FIG. 15C

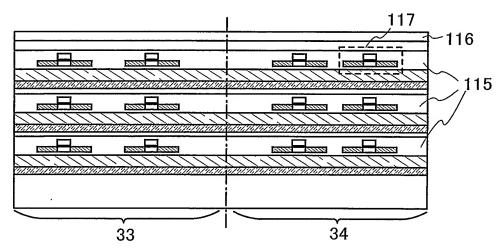
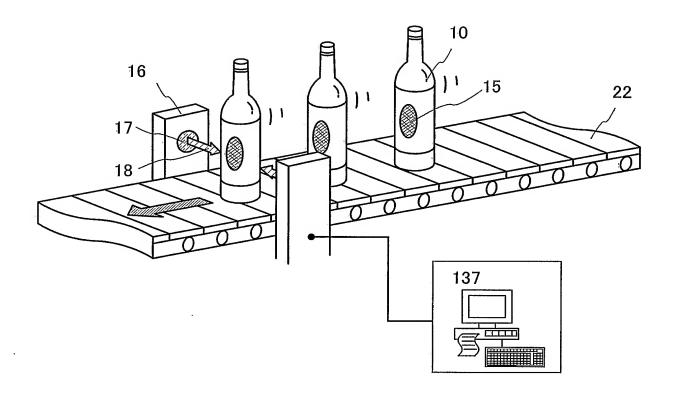


FIG. 16



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143 145 144 147

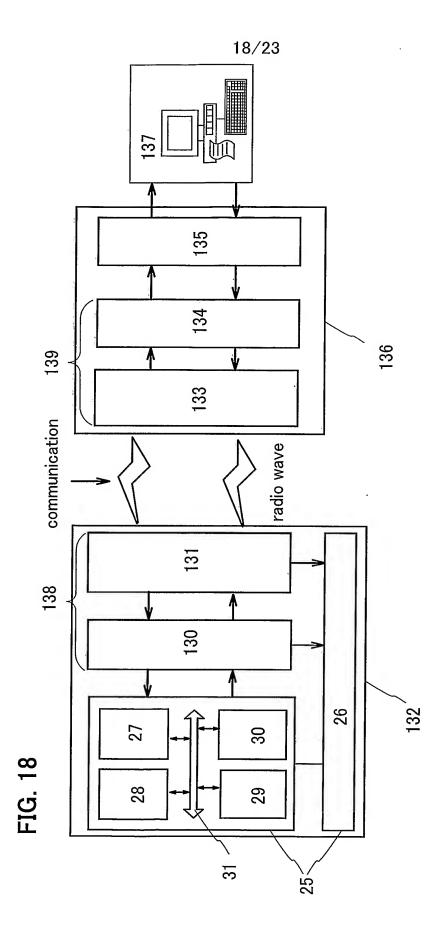
146

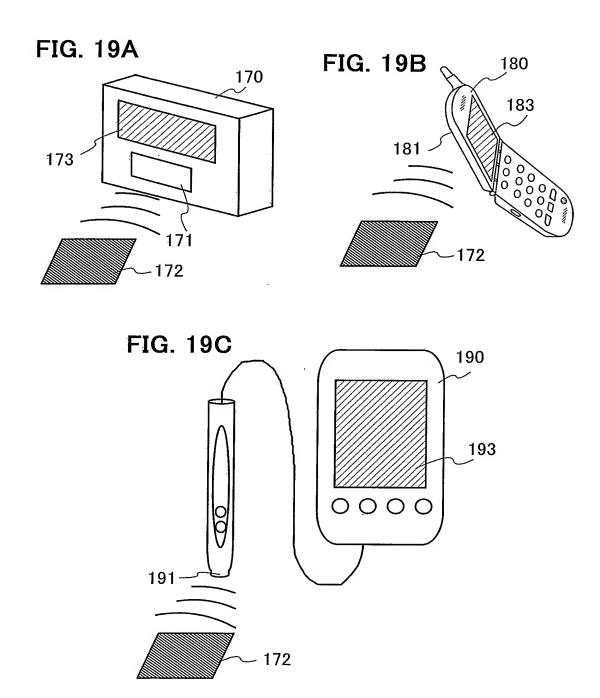
148

142

7 .

141





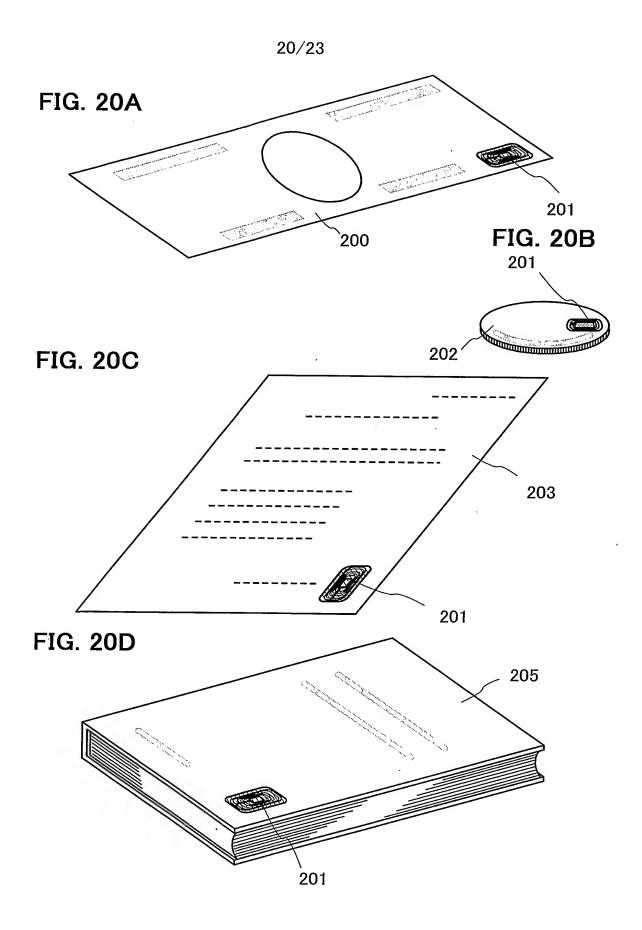


FIG. 21A

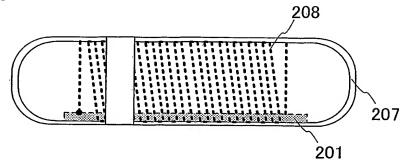


FIG. 21B

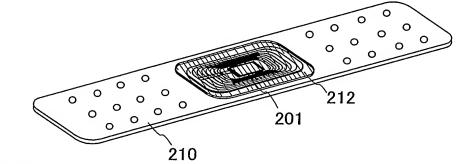
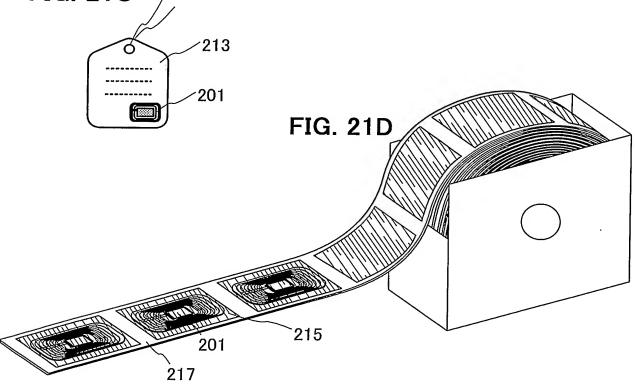


FIG. 21C



22/23 **EXPLANATION OF REFERENCE**

10 Product; 11 Label; 13 Small vacuum tweezer; 14 Adhesive material; 15 ID label; 16 Reader/writer; 17 Reader/writer antenna; 18 Radio wave; 19 Flexible substrate; 20 Antenna; 21 Connection portion; 22 Transportation means; 23 Resist; 25 Thin film integrated circuit; 26 Power supply circuit; 27 Input-output circuit; 28 Logic circuit; 29 Memory; 30 CPU; 33 CPU; 34 Memory; 35 Channel region; 36 Impurity region; 37 Gate insulating film; 38 Gate electrode; 41 Substrate; 42 Thin film integrated circuit; 43 Peel-off layer; 44 Base film; 45 Wiring; 46 Interlayer insulating film; 47 Interlayer insulating film; 48 Antenna; 49 Protective film; 50 Thin film integrated circuit device; 51 10 Temporary adhesive material; 52 Jig (a supporting substrate); 53 Halogen fluoride gas; 54 Resist; 55 Jig; 56 Substrate; 57 Planarizing film; 58 Projection; 60 Planarizing film; 61 Resist; 62 Contact portion; 63 Anisotropic conductive film; 64 Sealant; 66 Thin film integrated circuit device; 68 Antenna; 69 Substrate; 70 Flexible substrate; 71 Antenna; 73 Adhesive material; 74 Flexible substrate; 75 Element substrate; 76 Jig; 77 Projection; 15 78 Alignment mark; 79 Interlayer film; 81 Temporary adhesive material; 84 Product; 85 Adhesive material; 86 UV light; 87 Element (integrated circuit); 88 Cover; 89 Bell jar; 90 Substrate; 91 Heater; 92 Exhaust pipe; 93 Groove; 98 Connection portion; 99 Connection portion; 100 Island-shaped semiconductor film; 102 Gate insulating film; 103 Gate electrode; 104 Resist; 105 Insulating film; 106 Side wall (side wall); 107 Interlayer insulating film; 108 N-channel TFT; 109 P-channel TFT; 112 Antenna; 113 Upper wiring; 114 Antenna; 115 Interlayer film; 116 Protective film; 117 Thin film transistor; 118 Resist; 119 Impurity element; 120 Low concentration impurity region; 121 Resist; 122 Impurity element; 123 High concentration impurity region; 124 Resist; 125 Impurity element; 126 High concentration impurity region; 128 Wiring; 130 RF (radio) interface; Contactless interface; 132 Noncontact thin film integrated circuit device; 133 131 Contactless interface; 134 Interface circuit; 135 Controller; 136 Reader/writer; 137 Computer; 138 Antenna circuit; 139 Antenna circuit; 140 Producer (a manufacturer);141 Seller; 142 Consumer; 143 Product; 145 Sales information; 146 Purchase information; 147 Purchase information; 148 Commercial product information; 170 Main body of a

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reader/writer; 171 Sensor area; 172 Product; 173 Display area; 180 Main body of a cellular phone; 181 Sensor area; 183 Display area; 190 Main body of a reader; 191 Sensor area; 193 Display area; 200 Banknote; 201 Thin film integrated circuit device; 202 Coin; 203 Document; 205 Book; 207 Capsule; 208 Antenna; 210 Plaster; 212 Cover; 213 ID tag; 215 ID label; 217 Label board; 300 Apparatus; 301 Heater; 306 Wafer carrier; 307 Slurry; 308 Polishing pad; 309 Insulating film